

ABSTRACT

A resin for an undercoating material for forming an underlying film between a substrate and a photoresist layer, wherein the resin is a novolac resin containing 1% by mass or less, as measured by gel permeation chromatography, of low molecular weight components having a molecular weight of 500 or less. An undercoating material containing the resin, a laminate containing the undercoating material, and a resist pattern forming method using the undercoating material.